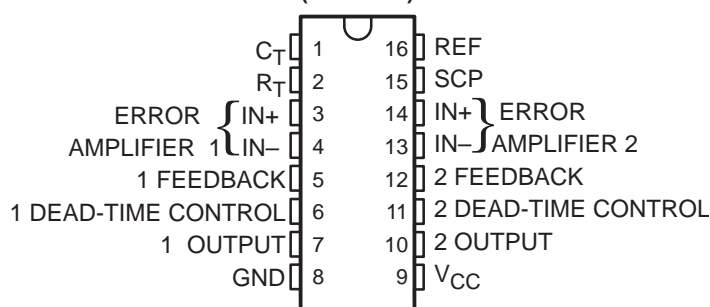


TL1453C DUAL PULSE-WIDTH-MODULATION CONTROL CIRCUIT

SLVS039A – FEBRUARY 1990 – REVISED DECEMBER 1990

- Complete PWM Power Control Circuitry
- Completely Synchronized Operation
- Internal Undervoltage Lockout Protection
- Wide Supply Voltage Range
- Oscillator Frequency . . . 500 kHz Max
- Variable Dead Time Provides Control Over Total Range
- Internal Regulator Provides a Stable 2.5-V Reference Supply

N OR NS PACKAGE
(TOP VIEW)



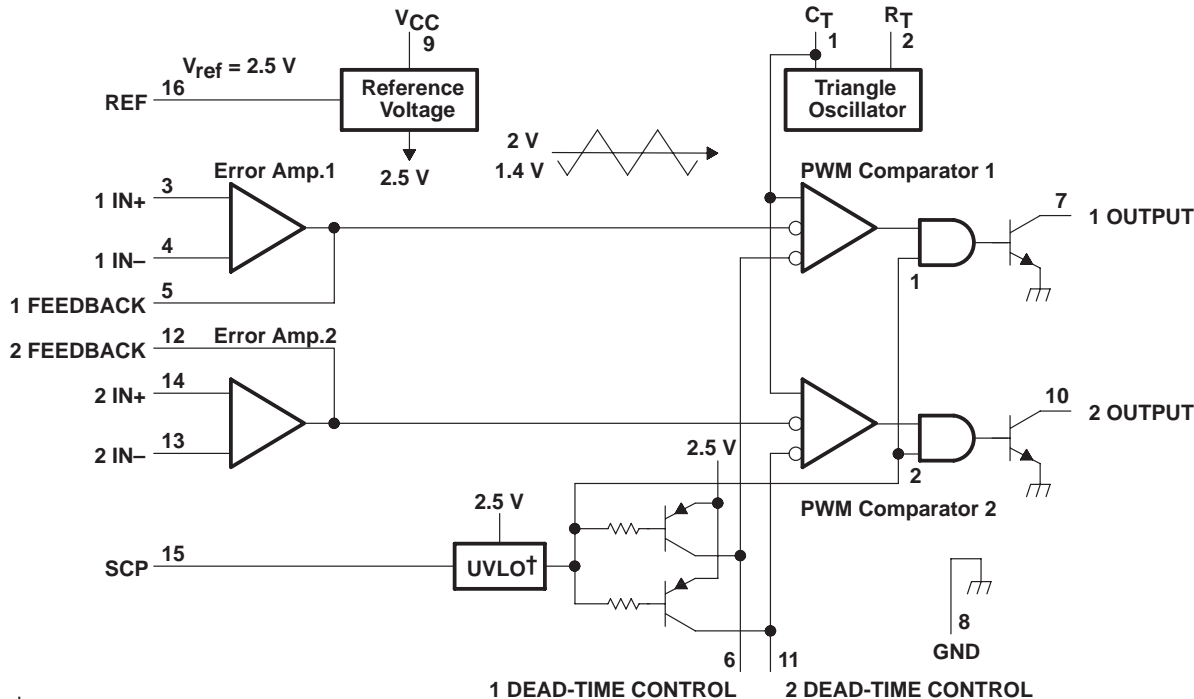
description

The TL1453C incorporates the functions required in the construction of two pulse-width-modulation control circuits on a single monolithic chip. Designed primarily for power supply control, the TL1453C contains an on-chip 2.5-V regulator, two error amplifiers, an adjustable oscillator, two dead-time comparators, undervoltage lockout circuitry, and dual common-emitter output transistor circuits.

The uncommitted output transistors provide common-emitter output capability for each controller. The internal amplifiers exhibit a common-mode voltage range from 1.05 V to 1.45 V. The dead-time control comparator has no offset unless externally altered and may be used to provide 0% to 100% dead time. The on-chip oscillator may be operated by terminating R_T (pin 2) and C_T (pin 1). During low- V_{CC} conditions, the undervoltage lockout control circuit feature inhibits the output until the internal circuitry is operational.

The TL1453C is characterized for operation from -20°C to 85°C .

functional block diagram



† UVLO = Undervoltage Lockout Protection

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 1990, Texas Instruments Incorporated

TL1453C

DUAL PULSE-WIDTH-MODULATION CONTROL CIRCUIT

SLVS039A – FEBRUARY 1990 – REVISED DECEMBER 1990

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	41 V
Amplifier input voltage	20 V
Collector output voltage	51 V
Collector output current	21 mA
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T_A	–20°C to 85°C
Storage temperature range	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

NOTE 1: All voltage values are with respect to network ground terminal.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25^\circ\text{C}$	$T_A = 85^\circ\text{C}$ POWER RATING
N	1000 mW	8 mW/°C	520 mW
NS	725 mW	5.8 mW/°C	397 mW

recommended operating conditions

	MIN	MAX	UNIT
Supply voltage, V_{CC}	3.6	40	V
Amplifier input voltage, V_I	1.05	1.45	V
Collector output voltage, V_O		50	V
Collector output current		20	mA
Current into feedback terminal		45	μA
Feedback resistor, R_F	100		kΩ
Timing capacitor, C_T	150	15000	pF
Timing resistor, R_T	5.1	100	kΩ
Oscillator frequency	1	500	kHz
Operating free-air temperature, T_A	–20	85	°C

electrical characteristics over recommended operating free-air temperature range, $V_{CC} = 6\text{ V}$, $f = 200\text{ kHz}$ (unless otherwise noted)

reference section

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Output voltage (pin 16)	$I_O = 1\text{ mA}$	2.4	2.5	2.6	V
Output voltage change with temperature	$T_A = -20^\circ\text{C}$ to 25°C	–0.1%		±1%	
	$T_A = 25^\circ\text{C}$ to 85°C	–0.2%		±1%	
Input regulation	$V_{CC} = 3.6\text{ V}$ to 40 V		2	12.5	mV
Output regulation	$I_O = 0.1\text{ mA}$ to 1 mA		1	7.5	mV
Short-circuit output current	$V_O = 0$	3	10	30	mA

† All typical values are at $T_A = 25^\circ\text{C}$.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

TL1453C

DUAL PULSE-WIDTH-MODULATION CONTROL CIRCUIT

SLVS039A – FEBRUARY 1990 – REVISED DECEMBER 1990

electrical characteristics over recommended operating free-air temperature range, $V_{CC} = 6\text{ V}$, $f = 200\text{ kHz}$ (unless otherwise noted) (continued)

undervoltage lockout section

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Upper threshold voltage (pin 9)	$I_{Oref} = 0.1\text{ mA}$, $T_A = 25^\circ\text{C}$		2.72		V
Lower threshold voltage (pin 9)	$I_{Oref} = 0.1\text{ mA}$, $T_A = 25^\circ\text{C}$		2.6		V
Hysteresis (pin 9)	$I_{Oref} = 0.1\text{ mA}$, $T_A = 25^\circ\text{C}$	80	120		mV

oscillator section

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Frequency	$C_T = 330\text{ pF}$, $R_T = 10\text{ k}\Omega$		200		kHz
Standard deviation of frequency	V_{CC} , T_A , R_T , C_T values are constant		10%		
Frequency change with voltage	$V_{CC} = 3.6\text{ V}$ to 40 V		1%		
Frequency change with temperature	$T_A = -20^\circ\text{C}$ to 25°C		-0.4%	$\pm 2\%$	
	$T_A = 25^\circ\text{C}$ to 85°C		-0.2%	$\pm 2\%$	

dead-time control section

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Input bias current (pins 6 and 11)				1	μA
Input threshold voltage at $f = 10\text{ kHz}$ (pins 6 and 11)	Zero duty cycle		2.05	2.25	V
	Maximum duty cycle	1.2	1.45		

error-amplifier section

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Input offset voltage	V_O (pins 5 and 12) = 1.25 V			± 6	mV
Input offset current	V_O (pins 5 and 12) = 1.25 V			± 100	nA
Input bias current	V_O (pins 5 and 12) = 1.25 V		160	500	nA
Common-mode input voltage range	$V_{CC} = 3.6\text{ V}$ to 40 V	1.05 to 1.45			V
Open-loop voltage amplification	$R_F = 200\text{ k}\Omega$	70	80		dB
Unity-gain bandwidth			1.5		MHz
Common-mode rejection ratio		60	80		dB
Positive output voltage swing		$V_{ref} - 0.1$			V
Negative output voltage swing				1	V
Output (sink) current (pins 5 and 12)	$V_{ID} = -0.1\text{ V}$, $V_O = 1.25\text{ V}$	0.5	1.6		mA
Output (source) current (pins 5 and 12)	$V_{ID} = 0.1\text{ V}$, $V_O = 1.25\text{ V}$	-45	-70		μA

output section

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Collector off-state current	$V_{CC} = 0$, $V_O = 50\text{ V}$			10	μA
	$V_O = 50\text{ V}$			10	
Output saturation voltage	$I_O = 10\text{ mA}$		1.2	2	V
Short-circuit output current	$V_O = 6\text{ V}$		90		mA

† All typical values are at $T_A = 25^\circ\text{C}$.

TL1453C
DUAL PULSE-WIDTH-MODULATION CONTROL CIRCUIT

SLVS039A – FEBRUARY 1990 – REVISED DECEMBER 1990

electrical characteristics over recommended operating free-air temperature range, $V_{CC} = 6\text{ V}$, $f = 200\text{ kHz}$ (unless otherwise noted) (continued)

pwm comparator section

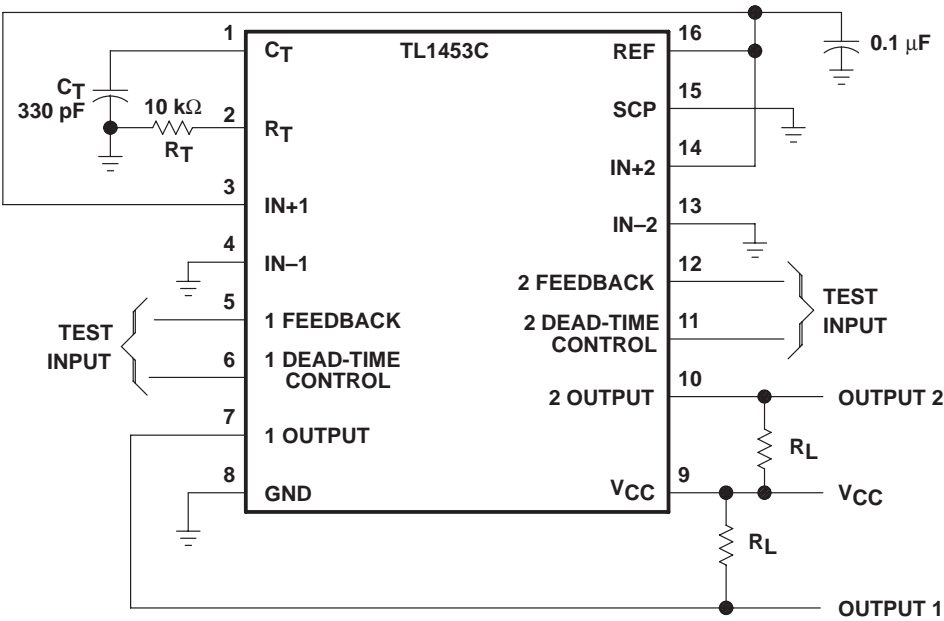
PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Input threshold voltage at $f = 10\text{ kHz}$ (pins 5 and 12)	Zero duty cycle		2.05	2.25	V
	Maximum duty cycle	1.2	1.45		
Input (sink) current (pins 5 and 12)	$V_I = 1.25\text{ V}$	0.5	1.6		mA
Input (source) current (pins 5 and 12)	$V_I = 1.25\text{ V}$	-45	-70		μA

total device

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Standby supply current	Off-state		1.3	1.8	mA
Average supply current	$R_T = 10\text{ k}\Omega$		1.7	2.4	mA

† All typical values are at $T_A = 25^\circ\text{C}$.

test circuit



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TL1453CD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL1453CDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL1453CN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL1453CNE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL1453CNSLE	OBSOLETE	SO	NS	16		TBD	Call TI	Call TI
TL1453CNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL1453CNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL1453CPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL1453CPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

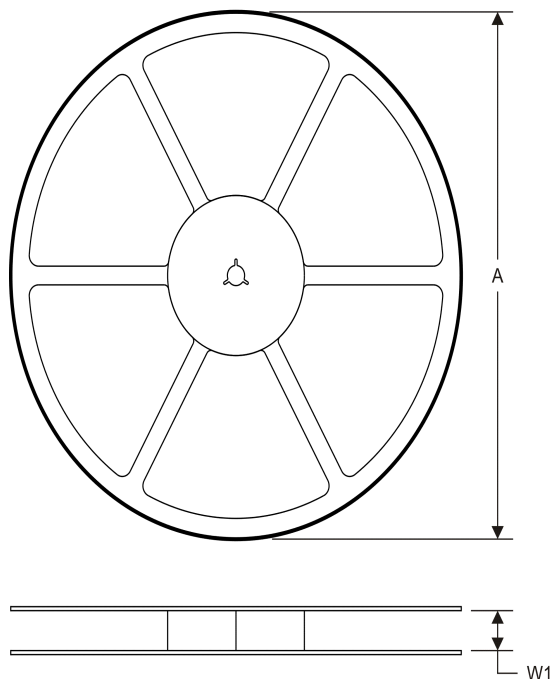
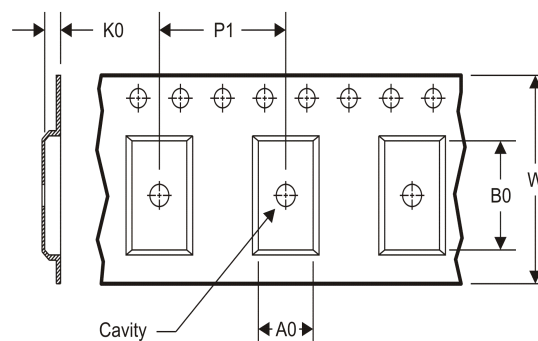
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL1453CNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
TL1453CPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL1453CNSR	SO	NS	16	2000	367.0	367.0	38.0
TL1453CPWR	TSSOP	PW	16	2000	367.0	367.0	35.0

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46C and to discontinue any product or service per JESD48B. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Mobile Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community e2e.ti.com